

**CPC COOPERATIVE PATENT CLASSIFICATION****C CHEMISTRY; METALLURGY***(NOTES omitted)***CHEMISTRY****C09 DYES; PAINTS; POLISHES; NATURAL RESINS; ADHESIVES; COMPOSITIONS NOT OTHERWISE PROVIDED FOR; APPLICATIONS OF MATERIALS NOT OTHERWISE PROVIDED FOR****C09G POLISHING COMPOSITIONS ([French polish C09F 11/00](#)); SKI WAXES**

- 1/00 Polishing compositions ([French polish C09F 11/00](#); [detergents C11D](#))**
- 1/02 . containing abrasives or grinding agents {(abrasives as such [C09K 3/14](#); polishing of semi-conductors [H01L](#))}
- 1/04 . Aqueous dispersions ([C09G 1/02](#) takes precedence)
- 1/06 . Other polishing compositions
- 1/08 . . based on wax
- 1/10 . . . based on mixtures of wax and natural or synthetic resin
- 1/12 . . . . mixtures of wax and silicon-containing polycondensates
- 1/14 . . based on non-waxy substances
- 1/16 . . . on natural or synthetic resins
- 1/18 . . . on other substances
- 3/00 Ski waxes**